

## Minutes of WP-meeting 238

### Attendance:

DESY: Leif Jönsson, Claus Kleinwort, Oliver Schäfer

Fuzebox: Takahiro Fusayasu, Jochen Kaminski, Ron Settles, Akira Sugiyama, Jan Timmermans

### General News:

Jochen discussed the LCTPC-CM, which will take place on May 31<sup>st</sup> and June 1<sup>st</sup> in Santander. There will be 2 joint sessions with the vertex and silicon tracking, and 1.5 days (6 sessions of 1.5-2h each) of LCTPC-CM. One session will be reserved for the CB meeting. Jochen will send a doodle poll to find out which is the most best time slot.

### News from the groups:

Leif reported, that the 5<sup>th</sup> carrier board has been returned to Lund. It was bump bonded on an adapter board, which can be mounted on the CERN readout system. Unfortunately, only few tests could be done, since there were defined areas of the chip which did not work. Leif thinks, that the bump bonding did not work well and therefore has sent the carrier board and adapter board back to the company. They will x-ray the system and in case of bad bump connections are found they will put it one more time into the reflow oven. The system is expected back very soon for further tests.

Akira told, that there will be a Japanese face-to-face meeting next week. Strategic discussions will take place to develop a road map for developing the Japanese module further and how to proceed with the gating tests.

Jan announced that Peter Kluit besides analyzing the data of the 160 GridPix test beam has also looked at the data collected during the 2 Octopuce test beam 2 years ago. Peter will present his results in the pixel-meeting next week, and a shortened version in one of the upcoming Wpmtgs.

### AOB:

The next workpackage meeting will take place on March 17<sup>th</sup>.